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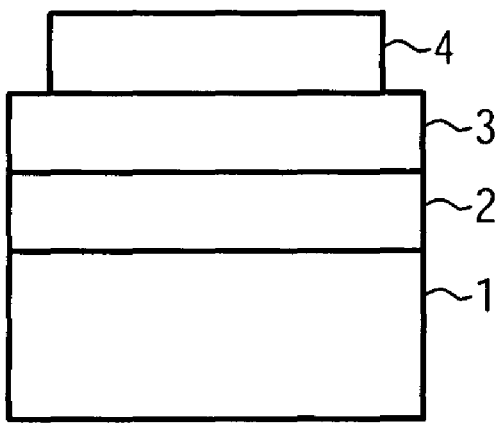
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(54) Title: STIFFENING LAYERS FOR THE RELAXATION OF STRAINED LAYERS

FIG. 1



(57) Abstract: The present invention relates to a method for relaxing a strained material layer, comprising providing a strained material layer and a low-viscosity layer formed on a first face of the strained material layer; forming a stiffening layer on at least one part of a second face of the strained material layer opposite to the first face thereby forming a multilayer stack; and subjecting the multilayer stack to a heat treatment thereby at least partially relaxing the strained material layer.